

Materials Declaration

Package	LFCSP
Body Size	5 X 5 X 0.85 (3.1 mm exposed pad)
LeadCount	32
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	1.98 E-02	257056
Multiaromatic Resin	16.0	3.78 E-03	48963
Subtotal		2.36 E-02	306019

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	3.44 E-02	527980
Fe	2.35	8.46 E-04	12726
Zn	0.12	4.20 E-05	650
P	0.03	1.10 E-05	162
Subtotal		3.53 E-02	541518

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100.0	7.40 E-04	12505

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	1.15 E-03	19639

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	8.43 E-04	15655

Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	5.05 E-03	86918

Die Attach Material

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	7.66 E-04	12422
Resin	21.0	2.30 E-04	3727
Metal Oxide	3.0	3.30 E-05	532
Amine	3.0	3.30 E-05	532
Gamma Butyrolactone	3.0	3.30 E-05	532
Subtotal		1.10 E-03	17745

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A13052. ICP-OES.
Cd	Not Detected	EPA Method 3051A13052. ICP-OES.
Hg	Not Detected	EPA Method 3051A13052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Material

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A13052. ICP-OES.
Cd	Not Detected	EPA Method 3051A13052. ICP-OES.
Hg	Not Detected	EPA Method 3051A13052. ICP-OES.
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
6.78 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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